

Reducing steady state losses in high performance charger topologies with easy-to-use GaN HEMTs

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OUTLINE

- Chargers design trends
- Topologies review for chargers
- Easy-to-use GaN HEMTs charger design
- Measurement results

Chargers design trends

CHARGER DESIGN TRENDS

Environmental sustainability:

- Standardize dc power connector, USB Type-C
- Reduce no load input power and increase charger efficiency at 10 % loading to 100 % loading

Users' requests:

- Charger designs for universal ac input voltage and variable output dc voltage
- Smaller form factors and shorter the charging times

Therefore, charger design trends

- High efficiency (>93 % @ 100 Vac full load) with low no load power consumption
- Output power: >65 W
- Power density increase:
 - 65 W charger around 1.2 W/cm^3
 - 75 W to 240 W charger around 1 W/cm^3 (including PFC stage)

SINGLE VOLTAGE EPS AC-DC

Efficiency in active mode – standard/basic voltage output ($\geq 6\text{ V}$)

Output Power	DoE Level VI 2016		DoE* (Feb 2023)	CoC Tier 2 2016	ErP 2020	PF
	Efficiency	PF	Efficiency	Efficiency	Efficiency	
0.3 W – 1 W	$\geq 0.517 P_{no} + 0.16$		$\geq 0.517 P_{no} + 0.091$	$\geq 0.5 P_{no} + 0.169$	$\geq 0.5 P_{no} + 0.16$	
1 W – 49 W	$\geq 0.071 \ln(P_{no}) - 0.0014 P_{no} + 0.67$		$\geq 0.0834 \ln(P_{no}) - 0.0011 P_{no} + 0.643$	$\geq 0.071 \ln(P_{no}) - 0.00115 P_{no} + 0.67$	$\geq 0.071 \ln(P_{no}) - 0.0014 P_{no} + 0.67$	
49 W – 250 W	≥ 0.88	≥ 0.9 at $115\text{ V}_{ac}/60\text{ Hz}$ for $P_{in} \geq 100\text{ W}$	≥ 0.902	≥ 0.89	≥ 0.88	EN-61000-3-2 Class D
>250 W	≥ 0.875		≥ 0.902	N/A	N/A	

No load power consumption – low voltage output and standard/basic voltage output

Output Power	DoE Level VI 2016	DoE* (Feb 2023)	CoC Tier 2 2016	ErP 2020
0.3 W-49 W	$\leq 100\text{ mW}$	$\leq 75\text{ mW}$	$\leq 75\text{ mW}$	$\leq 100\text{ mW}$
49 W – 250 W	$\leq 210\text{ mW}$	$\leq 75\text{ mW}$	$\leq 150\text{ mW}$	$\leq 210\text{ mW}$
>250 W	$\leq 500\text{ mW}$	$\leq 200\text{ mW}$	N/A	N/A

P_{no} : rated output power

*<https://www.govinfo.gov/content/pkg/FR-2023-02-02/pdf/2023-01282.pdf>

MULTIPLE VOLTAGE EPS AC-DC

Efficiency in active mode

Output Power	DoE Level VI 2016		DoE* (Feb 2023)	ErP 2020	
	Efficiency	PF	Efficiency	Efficiency	PF
0.3 W- 1 W	$\geq 0.497 P_{no} + 0.067$		$\geq 0.497 P_{no} + 0.067$	$\geq 0.497 P_{no} + 0.067$	
1 W – 49 W	$\geq 0.075 \ln(P_{no}) + 0.561$		$\geq 0.0782 \ln(P_{no}) - 0.0013 P_{no} + 0.643$	$\geq 0.075 \ln(P_{no}) + 0.561$	
49 W – 250 W	≥ 0.86	≥ 0.9 at 115 Vac /60 Hz for Pin ≥ 100 W	≥ 0.885	≥ 0.86	EN-61000-3-2 Class D
>250 W	≥ 0.86		≥ 0.885	N/A	

No load power consumption – low voltage output and standard/basic voltage output

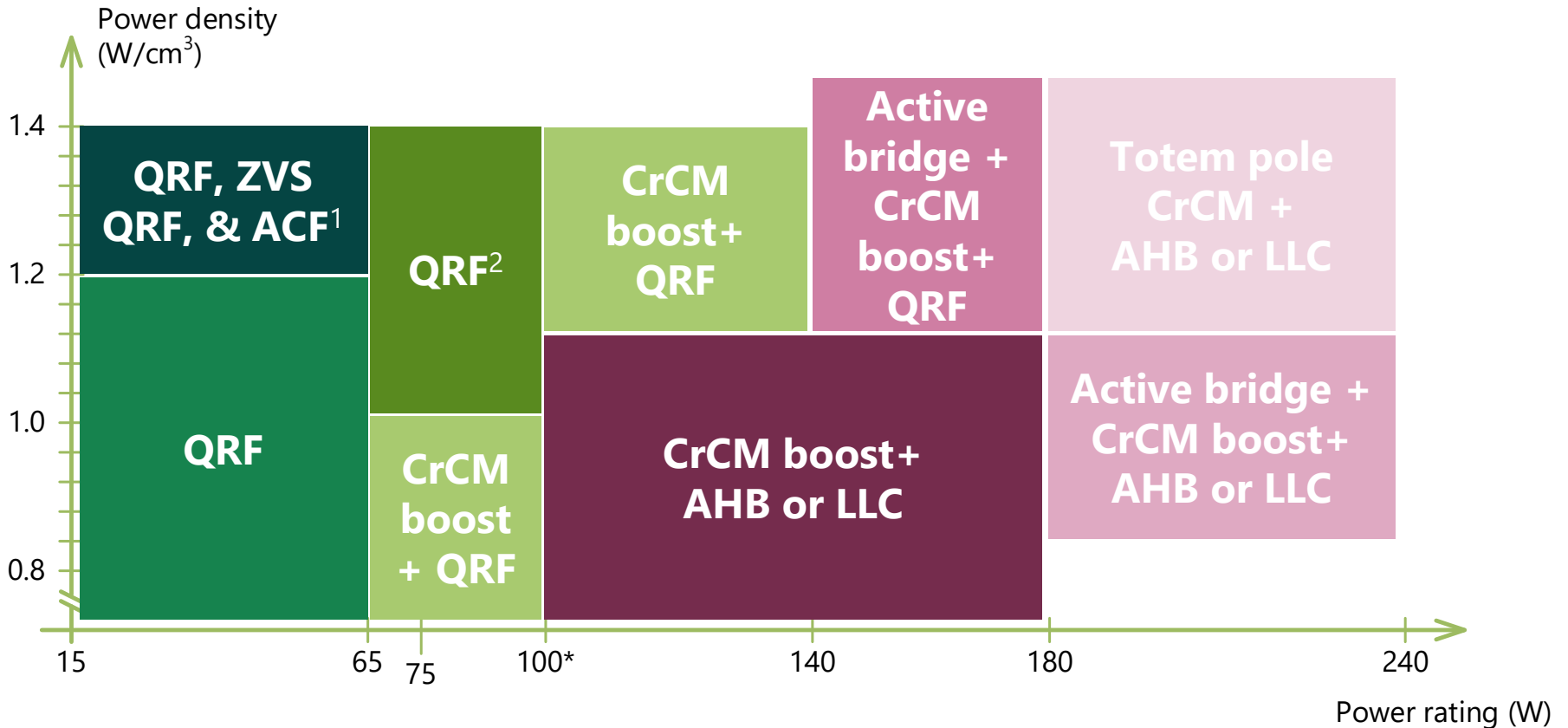
Output Power	DoE Level VI 2016	DoE* (Feb 2023)	ErP 2020
0.3 W-49 W	≤ 300 mW	≤ 75 mW	≤ 300 mW
49 W – 250 W	≤ 300 mW	≤ 125 mW	≤ 300 mW
>250 W	≤ 300 mW	≤ 125 mW	N/A

P_{no} : rated output power

*<https://www.govinfo.gov/content/pkg/FR-2023-02-02/pdf/2023-01282.pdf>

Topologies review for chargers

OUTPUT POWER VS TOPOLOGIES

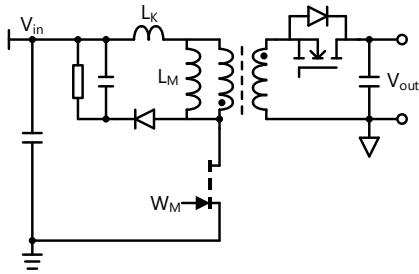


Remark: *input power rating

Remark: 1. ZVS QR and active-clamp flyback are usually designed for 65 W chargers. QR flyback is used when the output power is below 65 W

Remark: 2. Power factor is not required in DoE Level VI 2016 when input power below 100 W

FEATURES AND CHALLENGES FOR DC DC TOPOLOGIES



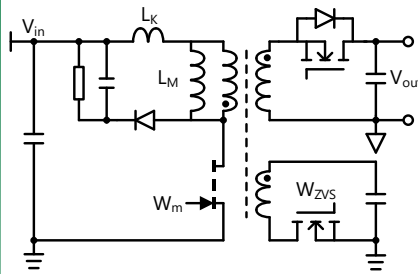
QR flyback

Features:

1. Low cost
2. Minimize component count
3. Easy control
4. Well-known EMI
5. Low no load input power

Challenges:

1. High switching losses
2. High voltage stress at main switch
3. No leakage energy recycle



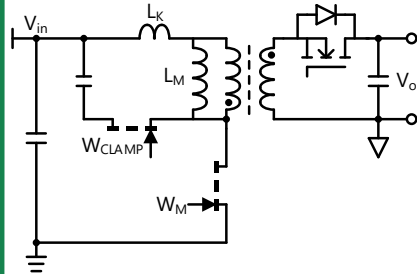
ZVS QR flyback

Features:

1. ZVS at HV switch
2. Similar control as QR flyback
3. Well-known EMI

Challenges:

1. High voltage stress at main switch
2. No leakage energy recycle
3. High component count
4. High no load input power



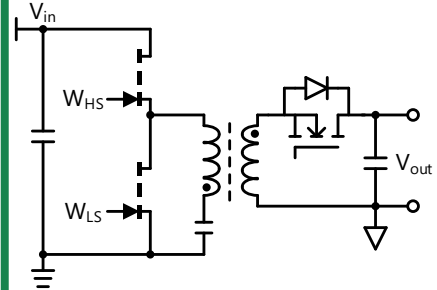
Active clamp flyback

Features:

1. ZVS at HV switches
2. Low voltage stress in switches
3. Leakage energy recycle

Challenges:

1. Complex control
2. High component count
3. High no load input power



Asymmetrical half-bridge

Features:

1. ZVS at HV switches
2. Low voltage stress and peak current stress in switches
3. Leakage energy recycle

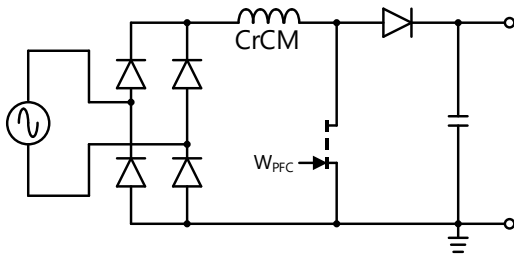
Challenges:

1. Complex control
2. High component count
3. High no load input power

COMPARISON OF EACH DC DC FOR CHARGER DESIGNS

Parameter	QR flyback	ZVS QR flyback	Active-clamp flyback (Complementary)	Asymmetrical half-bridge
Active component	<ul style="list-style-type: none"> • HV SW • Low side driver 	<ul style="list-style-type: none"> • HV SW • LV SW • 2 low side drivers 	<ul style="list-style-type: none"> • 2 HV SWs • Level shift driver • Low side driver 	<ul style="list-style-type: none"> • 2 HV SWs • Level shift driver • Low side driver
Passive component	<ul style="list-style-type: none"> • Transformer with additional winding for valley detection • RCD Snubber 	<ul style="list-style-type: none"> • Transformer with additional winding for ZVS • Resonant capacitor • RCD Snubber 	<ul style="list-style-type: none"> • Transformer • Clamping capacitor 	<ul style="list-style-type: none"> • Transformer • Resonant capacitor
Control complexity	<ul style="list-style-type: none"> • Simple 	<ul style="list-style-type: none"> • Moderate 	<ul style="list-style-type: none"> • Complex 	<ul style="list-style-type: none"> • Complex
Leakage inductor energy	<ul style="list-style-type: none"> • Lost 	<ul style="list-style-type: none"> • Lost 	<ul style="list-style-type: none"> • Recuperated 	<ul style="list-style-type: none"> • No leakage energy losses
ZVS of main SW	<ul style="list-style-type: none"> • Partially 	<ul style="list-style-type: none"> • Almost 	<ul style="list-style-type: none"> • Full 	<ul style="list-style-type: none"> • Full
Full load efficiency	<ul style="list-style-type: none"> • Moderate 	<ul style="list-style-type: none"> • Good 	<ul style="list-style-type: none"> • Best 	<ul style="list-style-type: none"> • Best
No load power (burst mode)	<ul style="list-style-type: none"> • Best 	<ul style="list-style-type: none"> • Good 	<ul style="list-style-type: none"> • Moderate 	<ul style="list-style-type: none"> • Moderate

FEATURES AND CHALLENGES FOR PFC TOPOLOGIES



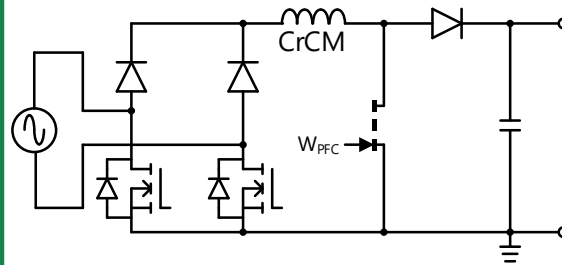
CrCM boost

Features:

1. Low cost
2. Minimize component count
3. Simple control
4. Well-known EMI

Challenges:

1. High rectifier bridge losses
2. High peak switch current
3. Limited output power



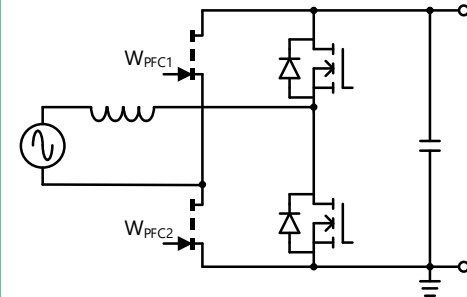
Active bridge + CrCM boost

Features:

1. Reduce bridge rectifier losses
2. Well-known EMI

Challenges:

1. High component count
2. High peak switches current
3. Cost



CrCM/CCM totem pole boost

Features:

1. No VF losses
2. High output power

Challenges:

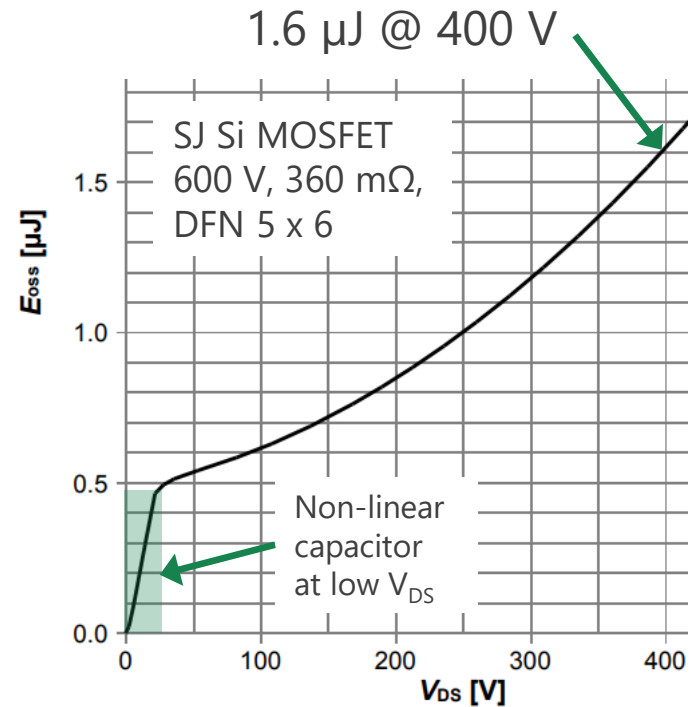
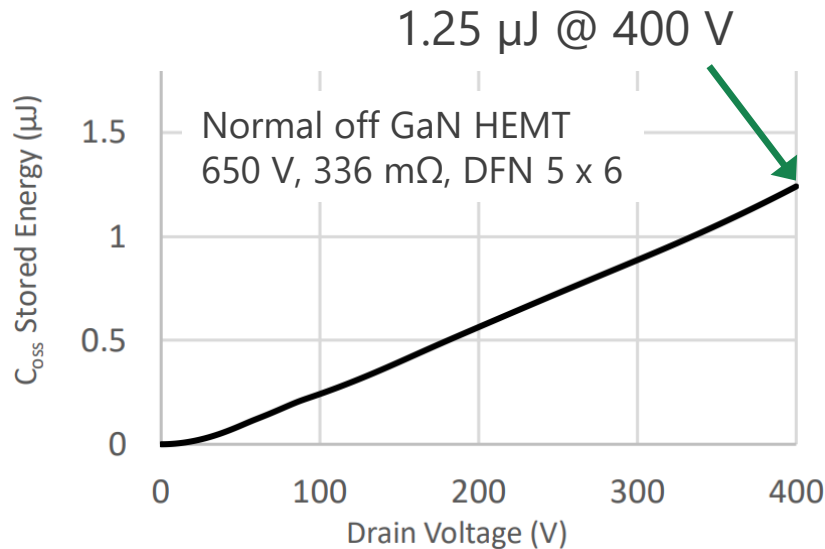
1. Floating driver
2. Complex control
3. EMI
4. Cost

Easy-to-use GaN HEMTs

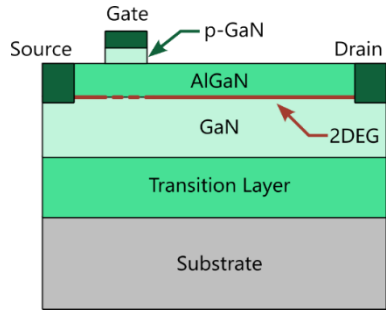
GAN HEMT VS SJ SILICON MOS

A small output capacitor, C_{OSS} , with linear characteristic switching devices can provide

- low switching losses in hard switching
- easy to achieve zero voltage switching
- fast switching frequency



EXISTING GAN HEMT SOLUTIONS



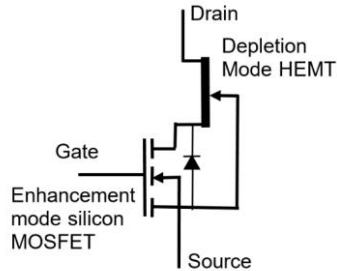
DISCRETE

Features:

1. Normally off operation
2. Two types gate contacts Ohmic or Schottky

Challenges:

1. Low threshold voltage $V_{th} \sim 1.5\text{ V}$
2. Low $V_{gs} \sim 7\text{ V}$
3. Negative driving voltages for turn-off



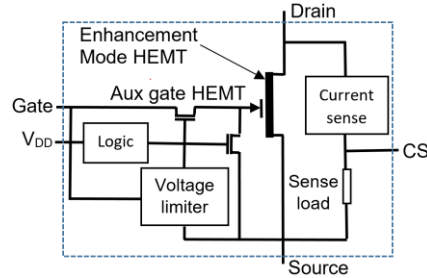
CASCODE

Features:

1. Easy to use drive provided by the silicon MOS gate
2. Low on-state forward drop in the reverse conduction mode

Challenges:

1. Reverse recovery losses at LV MOS
2. Slew rate control
3. High Q_g



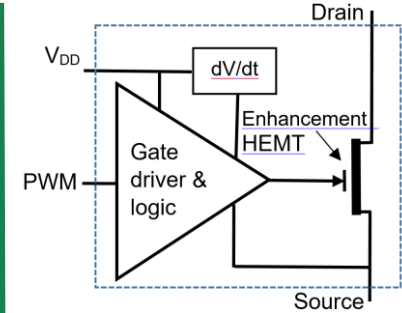
Monolithic integration

Features:

1. Driving interface attached to the HEMT gate
2. Extended gate voltage up to 20 V
3. Miller clamp for turn-off

Challenges

1. Extra chip area for the interface
2. Required driver IC



Monolithic integration with driver

Features:

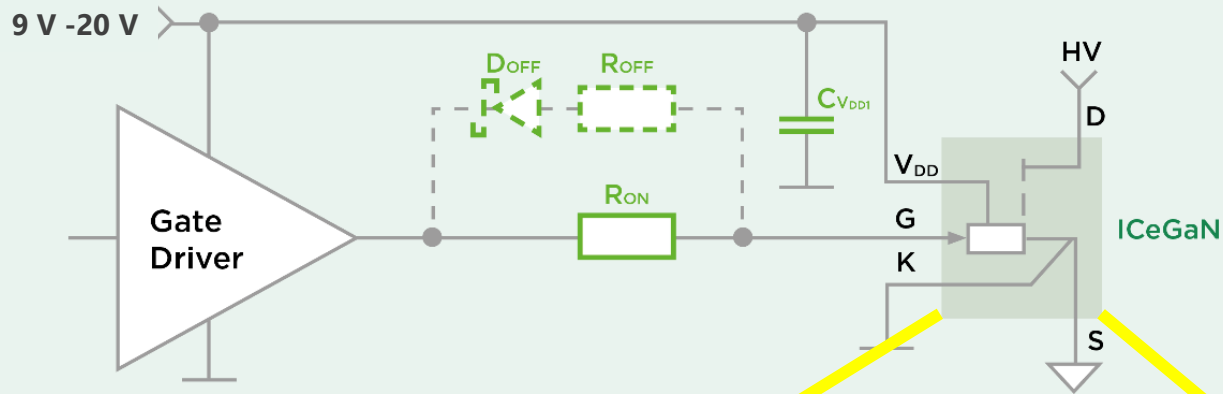
1. Robustness operation
2. Compact solution

Challenges:

1. Extra GaN chip area for the driver
2. Low driving current due to only n-channel LV GaN transistors is available (no p-channel).

EASY-TO-USE GAN HEMTS

Drive GaN like a MOSFET interface

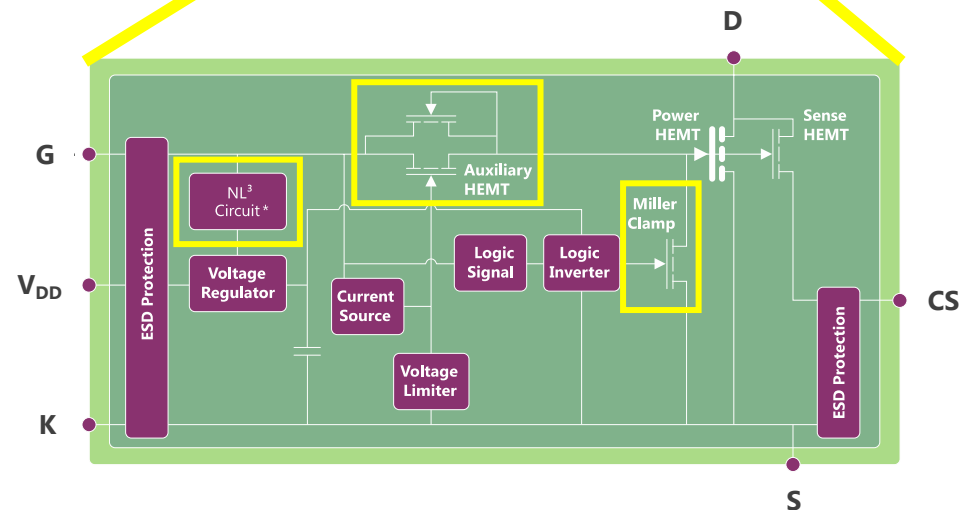


NL³ Circuit:

Improve no-load conditions, burst mode, and light load efficiency

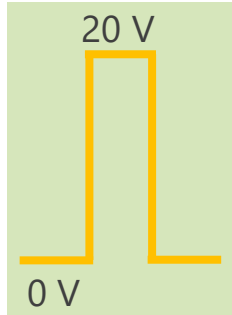
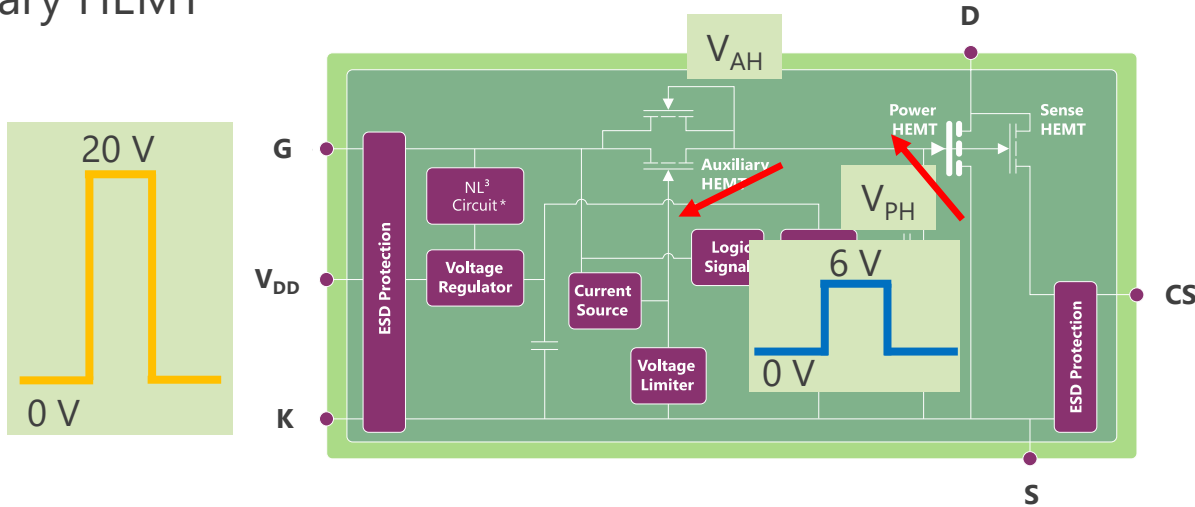
I_{VDD}	$V_{GS} = 12\text{ V}, V_{DS} = 0\text{ V}$	0.8	mA
I_{VDD}	$T_J = 150\text{ }^\circ\text{C}$ $V_{GS} = 12\text{ V}, V_{DS} = 0\text{ V}$	0.4	mA
I_{VDD}	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V}$	70	μA
I_{VDD}	$T_J = 150\text{ }^\circ\text{C}$ $V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V}$	35	μA

From datasheet CGD65B240SH2

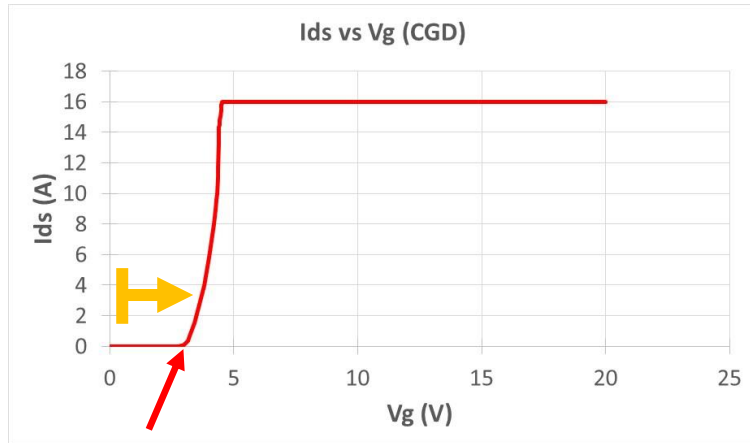


EASY-TO-USE GAN HEMTs

Auxiliary HEMT

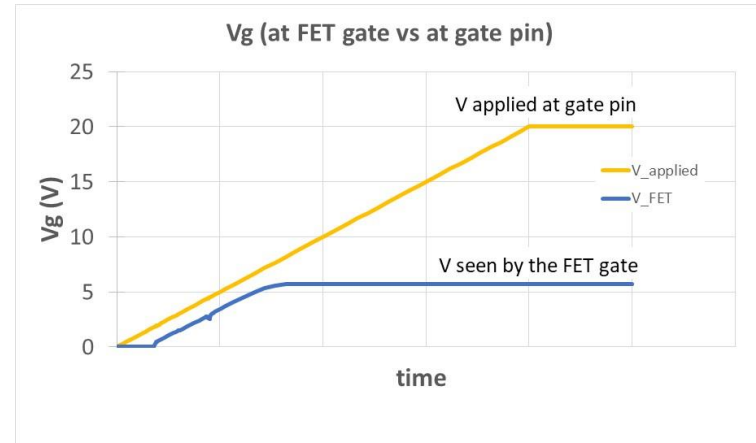


Increase the threshold voltage



$$V_{AH} + V_{PH}$$

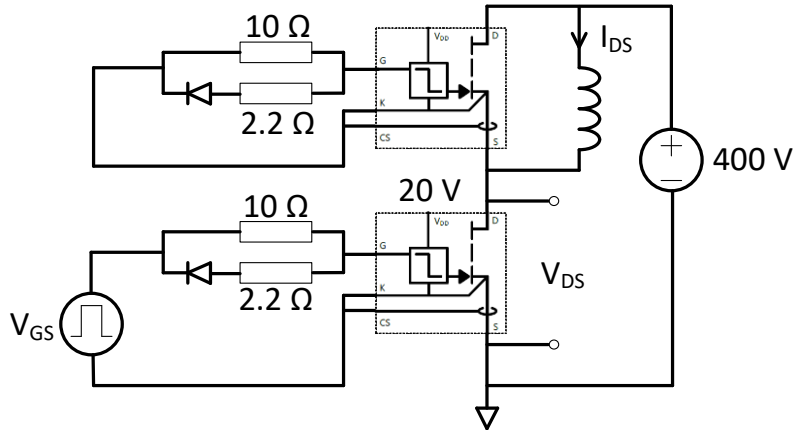
Clamping power HEMT gate voltage



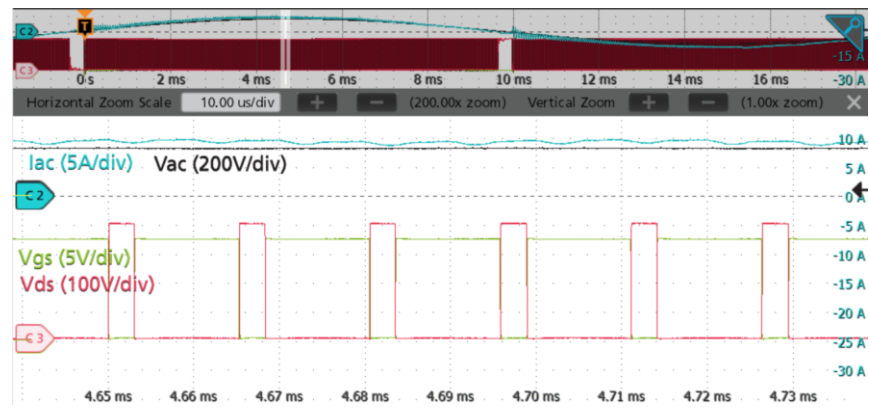
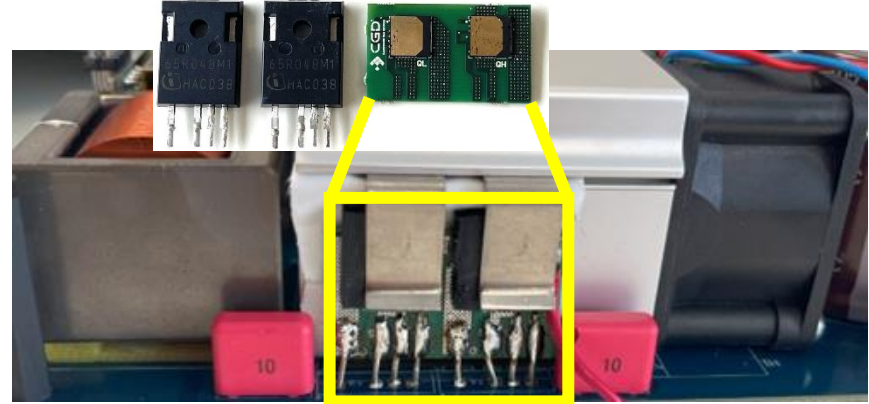
EASE-TO-USE GAN HEMTS

Miller clamp

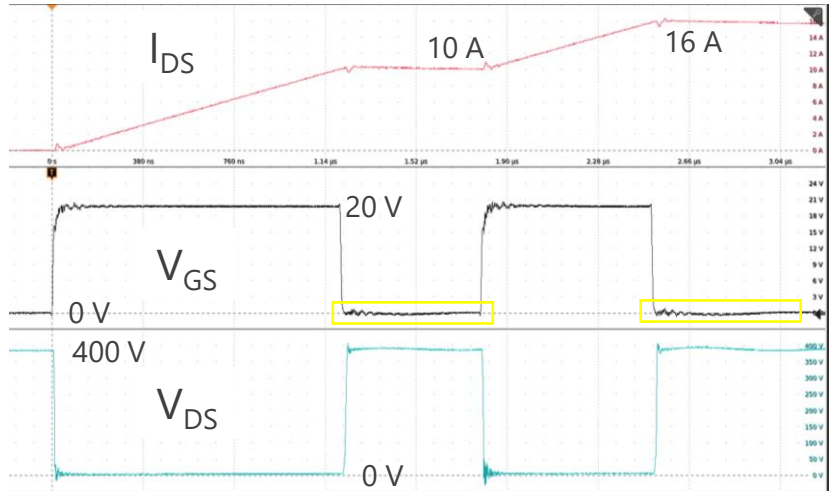
Double pulse test



Overcome return-on issue even had high parasitic inductance at source pin



ICeGaN 25 mohm top side cooled package.
Measured at 230 V_{AC} input voltage and 10 A_(peak) input current



Measured devices CGD65A055S2

Measurement results

100 W 2C 1A PD

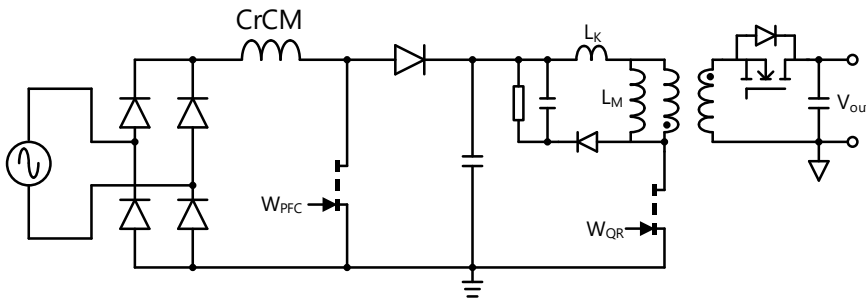
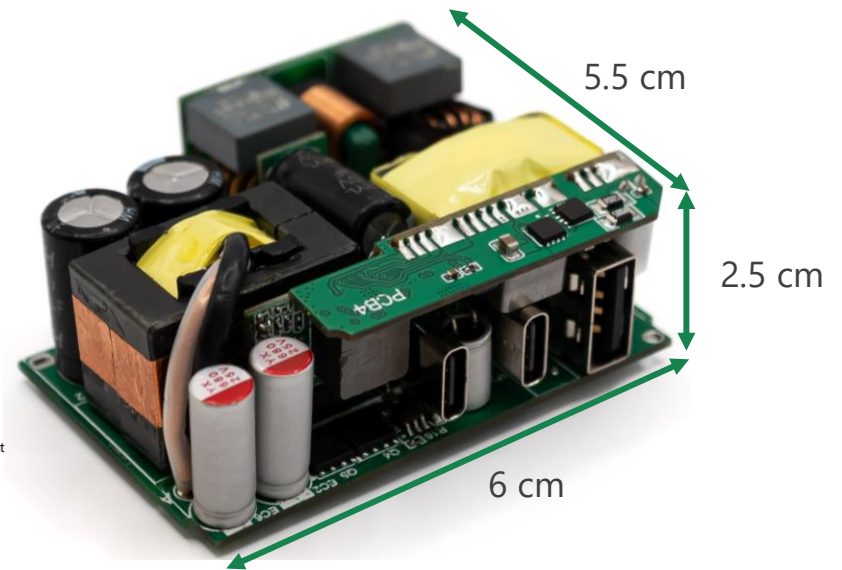
100 W PD REFERENCE DESIGN SPECIFICATION

Input voltage: 90 Vac/60 Hz, 115 Vac/60 Hz, 230 Vac/50 Hz, 264 Vac/50 Hz

Output voltage: 5 V (3 A), 9 V (3 A), 12 V (3 A), 15 V (3 A), 20 V (5 A)

Power density (PCBA): 0.825 W/cm³

CrCM boost + QR flyback + SR buck

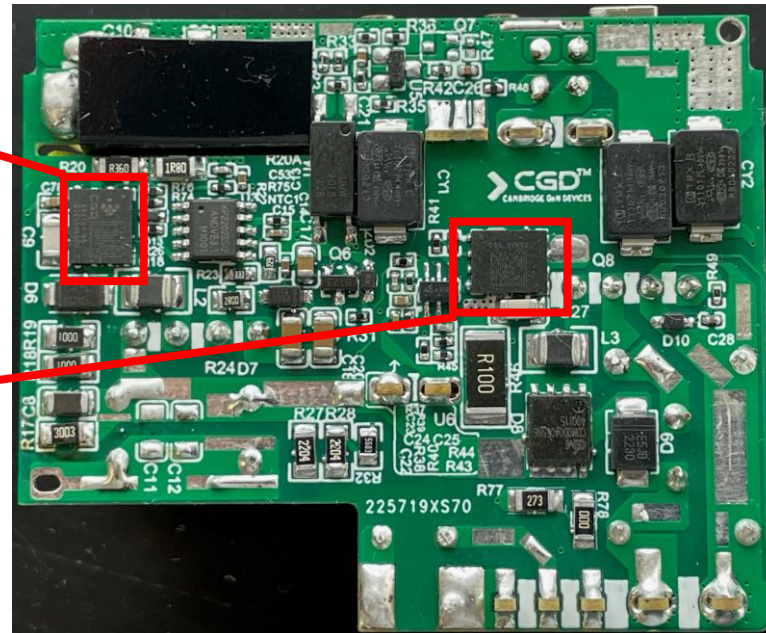


TOPOLOGY AND DEVICE USAGE

CrM boost + QR flyback + SR buck

CrM boost ICeGaN:
CGD65B200S2
(200 mohm, 650 V,
DFN 5 x 6)

QR flyback ICeGaN:
CGD65B240SH2
(240 mohm, 650 V, DFN 5 x 6)
H2 series ICeGaN incorporates
an advanced NL³ Circuit,
leading to record low power
losses at No Load and Light
Load operations.



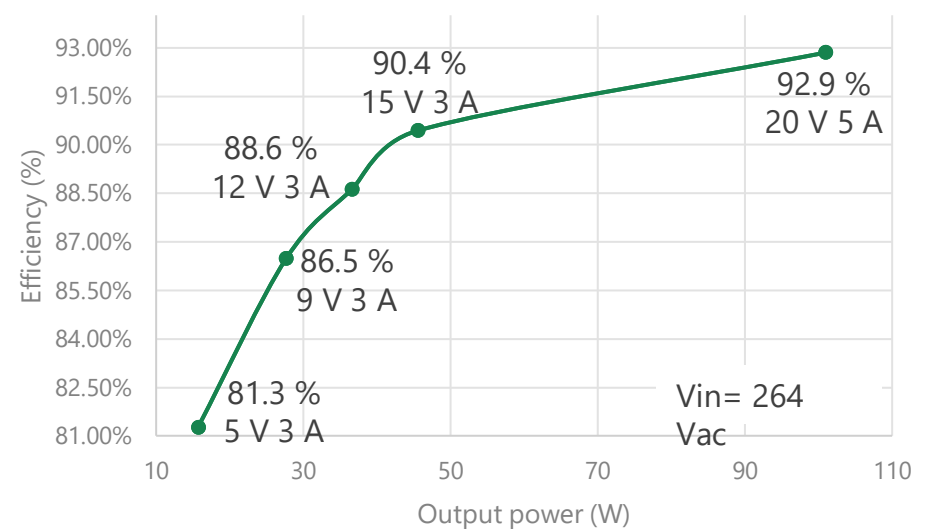
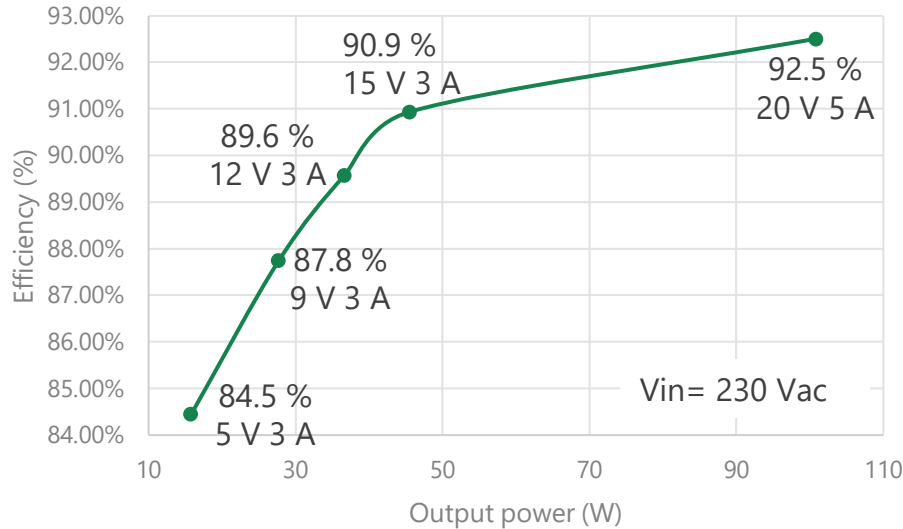
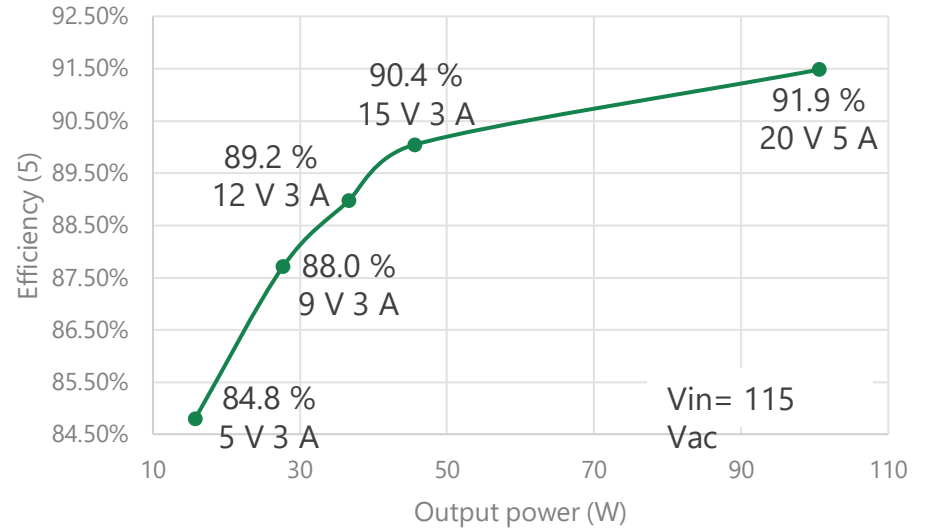
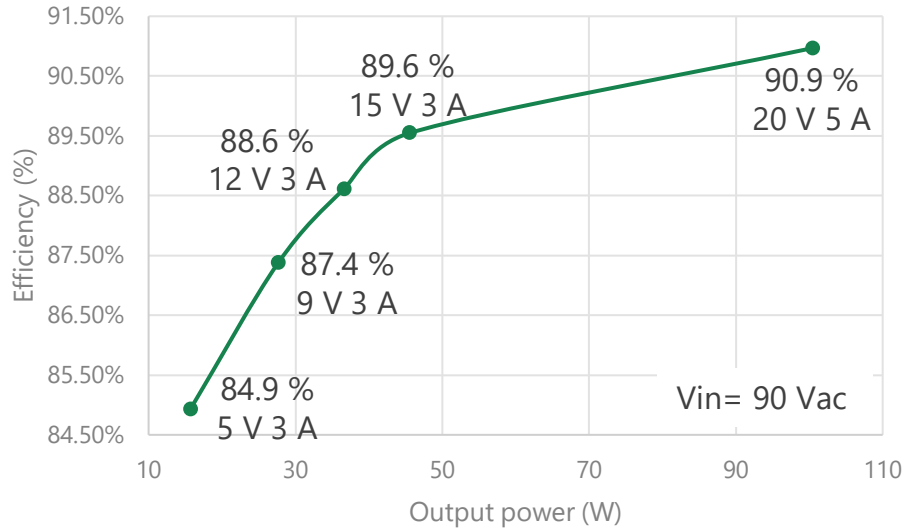
NO LOAD POWER CONSUMPTION

Output voltage ports = 5 V

Input voltage	No load input power only QR flyback	No load input power PFC stage + QR flyback	DoE Level VI 2016	ErP 2020
90 V	64 mW	185 mW	≤ 300 mW	≤ 300 mW
115 V	74 mW	195 mW		
230 V	130 mW	230 mW		
264 V	150 mW	284 mW		

EFFICIENCY MEASUREMENT AT TYPE C PORT

Full load at different output voltage



SUMMARY

The latest charger designs are requested low no-load power consumption, high efficiency, and high-power density

- no-load power consumption power reduce from 210 mW to 75 mW
- average efficiency increase from 88 % to 90.2 %

QR flyback is commonly selected topology in charger design

- minimize component count, easy control, low no load input power

GaN HEMT provides a linear and small output capacitor for fast discharging to achieve ZVS and reduces the switching losses at high switching frequency charger design

ICeGaN™ provides driving interface, NL³ circuit, voltage limiter, and Miller clamp